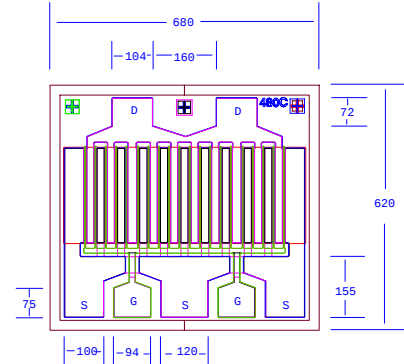


DATA SHEET
Low Distortion GaAs Power FET

- **+34.0dBm TYPICAL OUTPUT POWER**
- **18.0dB TYPICAL POWER GAIN AT 2GHz**
- **0.5 X 4800 MICRON RECESSED “MUSHROOM” GATE**
- **Si₃N₄ PASSIVATION AND PLATED HEAT SINK**
- **ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY**
- **Idss SORTED IN 80mA PER BIN RANGE**



Chip Thickness: 75 ± 13 microns
All Dimensions In Microns

ELECTRICAL CHARACTERISTICS (T_a = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
P_{1dB}	Output Power at 1dB Compression V _{ds} =8V, I _{ds} =50% I _{dss} f= 2GHz f= 4GHz	32.0	34.0 34.0		dBm
G_{1dB}	Gain at 1dB Compression V _{ds} =8V, I _{ds} =50% I _{dss} f= 2GHz f= 4GHz	16.0	18.0 12.5		dB
PAE	Gain at 1dB Compression V _{ds} =8V, I _{ds} =50% I _{dss} f= 2GHz		40		%
I_{dss}	Saturated Drain Current V _{ds} =3V, V _{gs} =0V	800	1360	1760	mA
G_m	Transconductance V _{ds} =3V, V _{gs} =0V	560	720		mS
V_p	Pinch-off Voltage V _{ds} =3V, I _{ds} =10mA		-2.0	-3.5	V
BV_{gd}	Drain Breakdown Voltage I _{gd} =4.8mA	-12	-15		V
BV_{gs}	Source Breakdown Voltage I _{gs} =4.8mA	-7	-14		V
R_{th}	Thermal Resistance (Au-Sn Eutectic Attach)		12		°C/W

MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²
V_{ds}	Drain-Source Voltage	12V	8V
V_{gs}	Gate-Source Voltage	-8V	-4V
I_{ds}	Drain Current	I _{dss}	1.2A
I_{gsf}	Forward Gate Current	120mA	20mA
P_{in}	Input Power	32dBm	@3dB Compression
T_{ch}	Channel Temperature	175°C	150°C
T_{stg}	Storage Temperature	-65/175°C	-65/150°C
P_t	Total Power Dissipation	11.4 W	9.5 W

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.

EFA480C

DATA SHEET

Low Distortion GaAs Power FET

S-PARAMETERS

8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.500	0.944	-119.8	9.669	115.5	0.023	33.8	0.515	-166.9
1.000	0.931	-149.2	5.352	97.6	0.026	24.2	0.553	-172.1
1.500	0.928	-161.0	3.646	88.3	0.027	23.1	0.564	-174.0
2.000	0.927	-167.6	2.756	81.6	0.027	24.4	0.569	-175.0
2.500	0.927	-172.0	2.213	75.9	0.028	26.6	0.574	-175.4
3.000	0.927	-175.4	1.849	70.7	0.029	29.2	0.580	-175.7
3.500	0.928	-178.1	1.587	66.0	0.030	31.9	0.585	-175.9
4.000	0.928	-179.6	1.389	61.4	0.031	34.6	0.591	-176.0
4.500	0.929	-177.5	1.235	57.0	0.032	37.2	0.597	-176.1
5.000	0.930	-175.6	1.112	52.8	0.034	39.6	0.604	-176.3
5.500	0.931	-173.9	1.010	48.7	0.035	41.9	0.612	-176.5
6.000	0.932	-172.3	0.925	44.7	0.037	44.1	0.620	-176.7
6.500	0.933	-170.7	0.853	40.8	0.039	46.0	0.628	-176.9
7.000	0.934	-169.2	0.790	37.0	0.040	47.8	0.636	-177.2
7.500	0.935	-167.7	0.735	33.3	0.042	49.4	0.645	-177.5
8.000	0.937	-166.3	0.687	29.7	0.044	50.8	0.654	-177.9
8.500	0.938	-164.9	0.643	26.2	0.047	52.1	0.664	-178.3
9.000	0.939	-163.6	0.604	22.8	0.049	53.2	0.673	-178.8
9.500	0.941	-162.3	0.569	19.5	0.051	54.1	0.683	-179.4
10.000	0.942	-160.9	0.537	16.2	0.054	54.9	0.693	-179.9

Note: The data included 0.7 mils diameter Au bonding wires:
2 gate wires, 20 mils each; 2 drain wires, 12 mils each; 6 source wires, 7 mils each.